

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	TLE8104E	**Issued**	31. January 2019
MA#	MA004926374		
Package	PG-DSO-20-71	**Weight***	598.01 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	10.435	1.74	1.74	17449	17449
leadframe	inorganic material	phosphorus	7723-14-0	0.051	0.01		85	
	non noble metal	zinc	7440-66-6	0.203	0.03		339	
	non noble metal	iron	7439-89-6	4.058	0.68		6785	
	non noble metal	copper	7440-50-8	164.755	27.55	28.27	275508	282717
wire	non noble metal	copper	7440-50-8	1.509	0.25	0.25	2523	2523
encapsulation	organic material	carbon black	1333-86-4	0.817	0.14		1366	
	plastics	epoxy resin	-	37.589	6.29		62857	
	inorganic material	silicondioxide	60676-86-0	370.171	61.90	68.33	619010	683233
leadfinish	non noble metal	tin	7440-31-5	4.487	0.75	0.75	7503	7503
plating	noble metal	silver	7440-22-4	0.767	0.13	0.13	1283	1283
glue	plastics	epoxy resin	-	0.791	0.13		1323	
	noble metal	silver	7440-22-4	2.373	0.40	0.53	3969	5292
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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